



Protect, strengthen and seal electronic components and parts

Unprotected electronics and PCBs are vulnerable to moisture, dust, vibration and damage. Overmoulding protects, strengthens and seals parts without damaging them.



Overmoulding using [Henkel Technomelt hotmelt adhesive](#) delivers effective IP rated packaging / enclosure, strain relief and cable sealing in one easy step.

The low-pressure process is fast. Technomelt solidifies in seconds and products can be tested immediately.

Ideal for battery packs, PCBs, micro-switches, sensors, connectors and wire harnesses – in fact all electronics encapsulation. Your strain relief design can take any form with as much built in flexibility as you need and also can include integrated part numbers and logos.

[Henkel Technomelt materials](#) are available from Overmould in white, clear, amber and black as standard and also a custom variety of colours.

[Download the Overmould
low pressure overmoulding brochure](#)